

Agenda - Wednesday October 8, 2025

9:00AM – 11:00 AM

09:00 AM - 10:30 AM		Technical Session 1: Passives, LEDs, WBG	Moderator: Uwe Berger	Hella (Forvia)
09:00 AM - 09:30 AM	T1.1	Tantalum Polymer Capacitors Trends and Challenges - Software Defined Vehicles (SDV)	Cristina MotaCaetano	Yageo
09:30 AM - 10:00 AM	T1.2	Need for speed? A Comparative Study of H2S-Corrosion Tests	Jennifer Rieder	amsOSRAM
10:00 AM - 10:30 AM	T1.3	HVM “Golden Recipe” Methodology for SiC Substrate Qualification Across Suppliers	Jay Rathert; Michael Schmalz	KLA / Volkswagen
10.30 AM - 11.00 AM		Break		

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11:00AM – 01:30 PM

11:00 AM - 11:30 AM		Technical Session 2: Invited Paper	Moderator: René Rongen	NXP Semiconductors
11:00 AM - 11:30 AM	T2.1	SAFETY in cars	Franck Galtie	NXP Semiconductors
11:30 AM - 12:00 PM	W1	Q102 / Optoelectronics	Uwe Berger	Hella (Forvia)
12:00 PM - 12:30 PM	W2	Q200	Alan Cooper	Yageo
12:30 PM - 01:30 PM		Lunch		

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01:30 PM – 4:15 PM

01:30 PM - 02:00 PM	W3	Q101 / Discretes	Andreas Pinkernelle	Nexperia
02:00 PM - 02:45 PM	W4	Wide Band Gap	Massimiliano Regardi	Nexperia
02:45 PM - 03:45 PM		Technical Session 3: Power Modules	Moderator: Martin Geiger	Microchip
02:45 PM - 03:15 PM	T3.1	Advanced Estimation of Remaining Useful Lifetime for Power Modules	Horst Lewitschnig	Infineon Technologies Austria AG
03:15 PM - 03:45 PM	T3.2	Thermal Fatigue in Copper Wire Bonds under Power Cycling: Acceleration Model and Influence of Different Wire Types	Carlo Neva	STMicroelectronics
03:45 PM - 04:15 PM		Break		

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04:15 PM – 05:00 PM

04:15 PM - 4:45 PM		Technical Session 3: Power Modules (cont'd)	Moderator: Martin Geiger	Nexperia
04:15 PM - 04:45 PM	T3.3	New HAST and non-destructive evaluation methods for Power Modules	Etienne Wortham	Nexperia
04:45 PM - 05:00 PM	W5	Q007 / Board Level Reliability	Romuald Roucou	STMicroelectronics
05:00 PM		Wrap-up Day 1		

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9:00AM – 11:00 AM

08:30 AM - 09:00 AM	W6	Extended Mission Profiles	Rene Rongen	NXP Semiconductors
09:00 AM - 10:30 AM		Technical Session 5: Extended/ Severe Mission Profiles	Moderator: Bassel Atala	STMicroelectronics
09:00 AM - 09:30 AM	T4.1	Extended Lifetime Evaluation – An OEM Point of View	Stefan Simon	Audi
09:30 AM - 10:00 AM	T4.2	Rethinking “Automotive”: How to Specify Components for Tomorrow’s Mobility	Francois Gouyou	Valeo
10:00 AM - 10:30 AM	T4.3	Considerations and Challenges in the Use of AEC-Q Components for Space Missions	Gonzalo Fernandez; Anastasia Pesce	Alter Technology / ESA
10.30 AM - 11.00 AM		Break		

Agenda - Thursday October 9, 2025

11:00AM – 01:30 PM

11:00 AM - 11:30 AM	W7	Q004 / Zero Defects & Q006 / Cu-wire	Rene Rongen	NXP Semiconductors
11:30 AM - 12:30 PM		Technical Session 6: Zero Defects	Bassel Atala	STMicroelectronics
11:30 AM - 12:00 PM	T5.1	Advancing Zero Defect Through Process-Oriented Reliability and Soft Error Risk Integration	Calvin Yang	SGS
12:00 AM - 12:30 PM	T5.2	Technical cleanliness for electronic components	Uwe Berger	Hella (Forvia)
12:30 PM - 01:30 PM		Lunch		

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01:30 PM – 03:00 PM

01:30 PM - 02:00 PM	W8	Q100 IC & CDC Template	Moderator: Bassel Atala	STMicroelectronics
02:00 PM - 03:00 PM		Technical Session 7: Zero Defects / Memory	Moderator: Martin Geiger	Microchip
02:00 PM - 02:30 PM	T6.1	Outliers Detection for Zero Defect on Non-Normal and Highly Multivariate Data	Francois Bergeret; Francois Bourlon	Ippon Innovation / NXP Semiconductors
02:30 PM - 03:00 PM	T6.2	Reliability Assessment of Single-Ended PCM in Automotive Microcontrollers Compliant with AEC-Q100 Standards	Fabio Dell'Orto	STMicroelectronics
03:00 PM - 03:30 PM		Break		

Agenda - Thursday October 9, 2025

03:00 PM – 04:15 PM

03:30 PM - 04:00 PM		Technical Session 8: ESD	Moderator: René Rongen	NXP Semiconductors
03:30 PM - 04:00 PM	T7.1	New Contact-Based CDM Methods Needed to Align with ESD Roadmap	Greg O'Sullivan; Sumit Tayal	Micron
04:00 PM - 04:15 PM	W9	Q104 / MCMs	Rene Rongen	NXP Semiconductors
04:15 PM		Wrap-up Day 2 and Closure		